

N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^{a, e}	Q _g (Max)			
60	0.023 at $V_{GS} = 10 \text{ V}$	50	66 nC			
60	0.027 at V _{GS} = 4.5 V	40	66 HC			

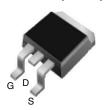
FEATURES

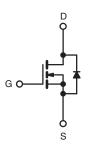
- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Logic-Level Gate Drive
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



HALOGEN FREE







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	60	V			
Gate-Source Voltage			V_{GS}	± 10	V	
Continuous Drain Current ^f	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I _D	50	А	
Continuous Drain Current	V _{GS} at 10 V	T _C = 100 °C		36		
Pulsed Drain Current ^a			I _{DM}	200		
Linear Derating Factor				1.0	- W/°C	
Linear Derating Factor (PCB Mount)e	,	0.025	VV/ C			
Single Pulse Avalanche Energy ^b	E _{AS}	400	mJ			
Maximum Power Dissipation $T_C = 25 ^{\circ}C$		В	150	W		
ximum Power Dissipation (PCB Mount) e $T_{A} = 25$: 25 °C	P_{D}	3.7	VV	
Peak Diode Recovery dV/dt ^c			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 175	°C			
Soldering Recommendations (Peak Temperature) ^d for 10 s		10 s		300 ^d		

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD} = 25$ V, starting $T_J = 25$ °C, L = 179 μ H, $R_g = 25$ Ω , $I_{AS} = 51$ A (see fig. 12). c. $I_{SD} \le 51$ A, $I_{AS} = 51$

- d. 1.6 mm from case.
- e. When mounted on 1" square PCB (FR-4 or G-10 material).
- f. Current limited by the package, (die current = 51 A).

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Maximum Junction-to-Ambient (PCB Mount) ^a	R _{thJA}	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.0		

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		<u> </u>		<u> </u>			ļ.
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		60	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.070	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1.0	-	3.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 10 V		-	-	± 100	nA
	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V		-	-	25	μΑ
Zero Gate Voltage Drain Current		V _{DS} = 48 V	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 150 °C		-	250	
Duain Cauras On State Registeres	R _{DS(on)}	V _{GS} = 10 V	I _D = 21 A ^b	-	23	-	Ω
Drain-Source On-State Resistance		V _{GS} = 4.5 V	I _D = 15 A ^b	-	27	-	
Forward Transconductance	9 _{fs}	V _{DS} = 25 V, I _D = 21A ^b		23	-	-	S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ f = 1.0 MHz, see fig. 5		-	3000	-	pF
Output Capacitance	C _{oss}			-	1000	-	
Reverse Transfer Capacitance	C _{rss}			-	200	-	
Total Gate Charge	Q_g			-	60	-	nC
Gate-Source Charge	Q_{gs}	$V_{GS} = 5.0 \text{ V}$	$I_D = 51 \text{ A}, V_{DS} = 48 \text{ V},$ see fig. 6 and 13^b	-	10	-	
Gate-Drain Charge	Q_{gd}			-	40	-	
Turn-On Delay Time	t _{d(on)}			-	17	-	200
Rise Time	t _r	V _{DD} :	= 30 V, I _D = 51 A,	-	230	-	
Turn-Off Delay Time	$t_{d(off)}$	$R_g = 4.6 \Omega$, $R_D = 0.56 \Omega$, see fig. 10 ^b		-	42	-	ns
Fall Time	t _f			-	110	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from		-	4.5	-	nЦ
Internal Source Inductance	L _S	package and center of die contact		-	7.5	-	nH
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the		-	-	50°	Α
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode		-	-	200	
Body Diode Voltage	V_{SD} $T_{J} = 25 ^{\circ}\text{C}, I_{S} = 51 \text{A}, V_{GS} :$		S_{c} , $I_{S} = 51$ A, $V_{GS} = 0$ V ^b	-	_	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T 05 00 54 A 41/44 400 A/ -b		-	130	180	ns
Body Diode Reverse Recovery Charge	Q_{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 51 \text{A}, dI/dt = 100 \text{A}/\mu\text{s}^b$			0.84	1.3	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-		-on is dor	ninated by L _S and L _D)		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.
 c. Current limited by the package, (Die Current = 51 A).



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

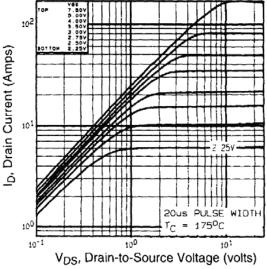


Fig. 2 - Typical Output Characteristics, $T_C = 150 \, ^{\circ}\text{C}$

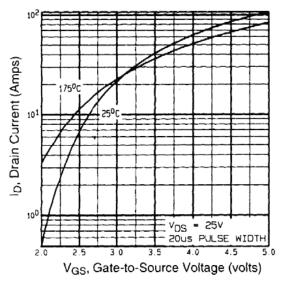


Fig. 3 - Typical Transfer Characteristics

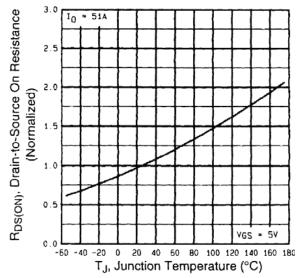


Fig. 4 - Normalized On-Resistance vs. Temperature



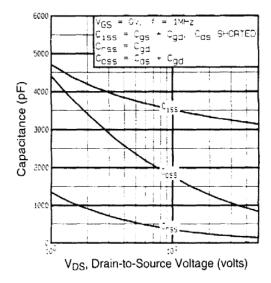


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

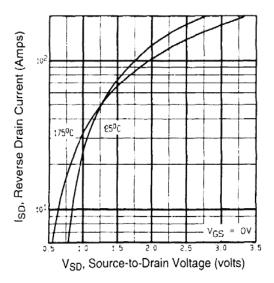


Fig. 7 - Typical Source-Drain Diode Forward Voltage

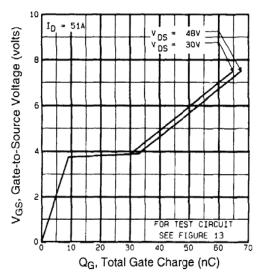


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

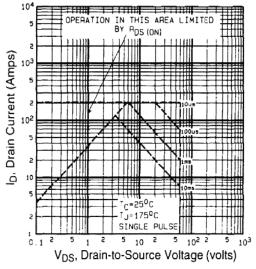


Fig. 8 - Maximum Safe Operating Area



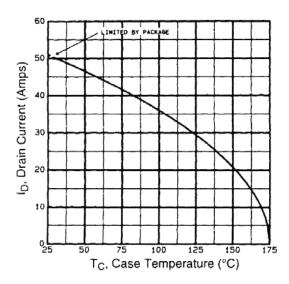


Fig. 9 - Maximum Drain Current vs. Case Temperature

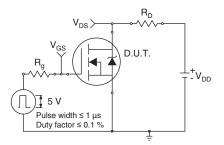


Fig. 10a - Switching Time Test Circuit

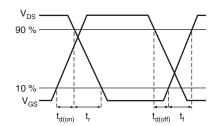


Fig. 10b - Switching Time Waveforms

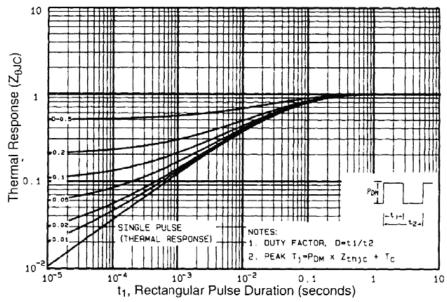
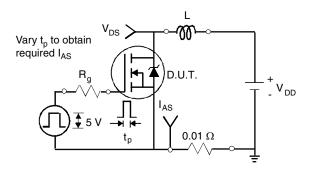


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case





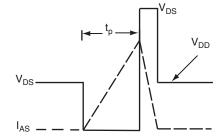


Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

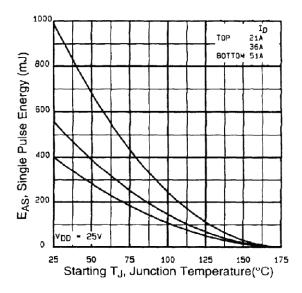


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

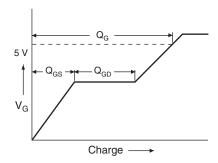


Fig. 13a - Basic Gate Charge Waveform

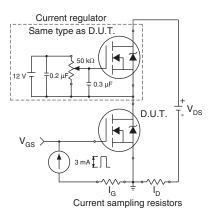
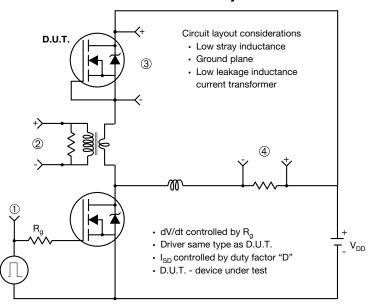


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



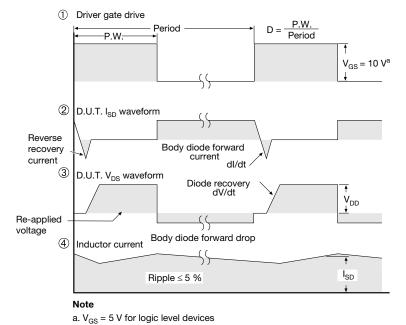
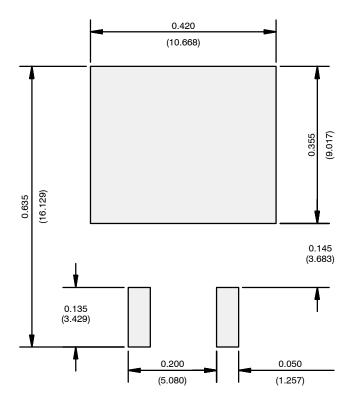


Fig. 14 - For N-Channel



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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